CUI DEVICES

ate 06/25/2021

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MODEL: HSS15-B20-P40 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- solder pin
- aluminum alloy
- black anodized finish





thermal resistance¹ power dissipation¹ @ 1 W, 400 LFM @ 75°C ∆T, @ 75°C ∆T, @ 1 W, @ 1 W, 200 LFM nat conv nat conv nat conv (°C/W) (°C/W) (°C/W) (°C/W) (W) HSS15-B20-P40 15.16 18.6 8.5 6.2 4.95

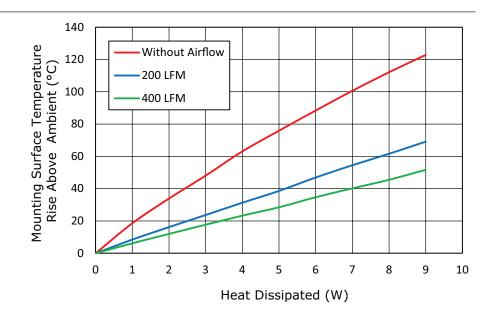
Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	18.6	8.5	6.2
2	33.9	16.2	12.0
3	48.1	23.7	17.7
4	63.1	31.3	23.3
5	75.9	38.6	28.5
6	88.4	46.9	34.7
7	100.6	54.5	40.2
8	112.1	61.6	45.5
9	122.8	69.1	51.7

Ths: "hot spot" temperature measured on the heatsink

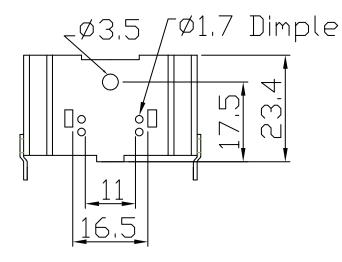
Ta: ambient temperature

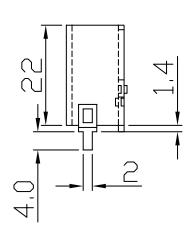


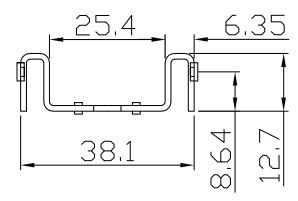
MECHANICAL DRAWING

units: mm tolerance: ±0.3 mm

MATERIAL	AL 1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	copper alloy
PIN PLATING	2∼3 µm tin
WEIGHT	1.6 g







Additional Resources: Product Page

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REVISION HISTORY

rev.	description	date
1.0	initial release	06/25/2021

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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